## IN THE CLAIMS:

- 1. (Original) A curable silicone composition comprising:
  - (A) an organopolysiloxane that has a branched molecular structure and contains in one molecule at least two univalent hydrocarbon groups with phenolic hydroxyl groups therein;
  - (B) a linear-chain organopolysiloxane having at least two univalent hydrocarbon groups with epoxy groups that are free of aromatic rings; and
  - (C) a curing accelerator.
- 2. (Original) The curable silicone composition of Claim 1, further comprising a filler (D).
- 3. (Previously Presented) The curable silicone composition according to Claim 1, wherein said component (A) is represented by the following silicone unit formula (1):

$$[R^{1}_{3}SiO_{1/2}]_{a}[R^{2}_{2}SiO_{2/2}]_{b}[R^{3}SiO_{3/2}]_{c}$$
(1)

(where  $R^1$ ,  $R^2$ , and  $R^3$  are  $C_{1\text{-}20}$  organic groups, at least two of which are univalent hydrocarbon groups with phenolic hydroxyl groups; «a + b + c =1»; «a», on average, satisfies the following condition: « $0 \le a \le 0.8$ », «b», on average, satisfies the following condition: « $0 \le b \le 0.8$ », and, «c», on average, satisfies the following condition: « $0.2 \le c \le 1.0$ »).

4. (Previously Presented) The curable silicone composition according to Claim 1, wherein said component (A) is represented by the following silicone unit formula (2):

$$[R^{4}_{3}SiO_{1/2}]_{d} [R^{5}_{2}SiO_{2/2}]_{e} [SiO_{4/2}]_{f}$$
(2)

(where  $R^4$ ,  $R^5$  are  $C_{1\text{--}20}$  organic groups, at least two of which are univalent hydrocarbon groups with phenolic hydroxyl groups; «d + e + f =1»; «d/f», on average, satisfies the following condition: « $0.02 \le d/f \le 4$ », «d», on average, satisfies the following condition: « $0 < d \le 0.8$ », «e», on average, satisfies the following condition: « $0 \le e \le 0.98$ ». and «f», on average, satisfies the following condition: « $0.002 \le f \le 0.98$ »).

- 5. (Previously Presented) The curable silicone composition according to Claim 1, wherein said component (A) is a liquid.
- 6. (Original) The curable silicone composition of Claim 3, wherein in said formula (1) that represents component (A), «a» satisfies the following condition: « $0 < a \le 0.8$ » and «b» is equal to 0.
- 7. (Previously Presented) The curable silicone composition according to Claim 1, wherein said component (B) is an organopolysiloxane represented by the following structural formula (3):

$$R^{7}_{3}SiO(R^{8}_{2}SiO)_{m}SiR^{7}_{3}$$
 (3)

(wherein  $R^7$  and  $R^8$  are the same or different  $C_{1-20}$  organic groups, at least two of which are univalent hydrocarbon groups with epoxy groups that are free of aromatic rings, and «m» is an integer between 0 and 1000).

- 8. (Previously Presented) The curable silicone composition according to Claim 1, wherein component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) is used in an amount of 0.01 to 100 parts by weight per 100 parts by weight of component (A).
- 9. (Previously Presented) The curable silicone composition according to Claim 1, wherein said univalent hydrocarbon group with epoxy group of said component (B) is an alkyl group bonded to a glycidoxy group or an alkyl group bonded to 3,4-epoxycyclohexyl group.
- 10. (Previously Presented) The curable silicone composition according to Claim 1, which is a liquid or a paste.
- 11. (Currently Amended) A cured product obtained by curing a curable silicone composition as claimed in any of Claim 1.
- 12. (Cancelled)
- 13. (Previously Presented) The curable silicone composition according to Claim 2, wherein said component (A) is represented by the following silicone unit formula (1):

$$[R^{1}_{3}SiO_{1/2}]_{a}[R^{2}_{2}SiO_{2/2}]_{b}[R^{3}SiO_{3/2}]_{c}$$
(1)

(where  $R^1$ ,  $R^2$ , and  $R^3$  are  $C_{1-20}$  organic groups, at least two of which are univalent hydrocarbon groups with phenolic hydroxyl groups; «a + b + c =1»; «a», on average, satisfies the following

condition:  $<0 \le a \le 0.8$ », <b», on average, satisfies the following condition:  $<0 \le b \le 0.8$ », and, <c», on average, satisfies the following condition:  $<0.2 \le c \le 1.0$ »).

14. (Previously Presented) The curable silicone composition according to Claim 2, wherein said component (A) is represented by the following silicone unit formula (2):

$$[R^{4}_{3}SiO_{1/2}]_{d} [R^{5}_{2}SiO_{2/2}]_{e} [SiO_{4/2}]_{f}$$
(2)

(where  $R^4$ ,  $R^5$  are  $C_{1\text{-}20}$  organic groups, at least two of which are univalent hydrocarbon groups with phenolic hydroxyl groups; «d + e + f =1»; «d/f», on average, satisfies the following condition: « $0.02 \le d/f \le 4$ », «d», on average, satisfies the following condition: « $0 < d \le 0.8$ », «e», on average, satisfies the following condition: « $0 \le e \le 0.98$ ». and «f», on average, satisfies the following condition: « $0.002 \le f \le 0.98$ »).

- 15. (Previously Presented) The curable silicone composition according to Claim 2, wherein said component (A) is a liquid.
- 16. (Previously Presented) The curable silicone composition of Claim 13, wherein in said formula (1) that represents component (A), «a» satisfies the following condition: « $0 < a \le 0.8$ » and «b» is equal to 0.
- 17. (Previously Presented) The curable silicone composition according to Claim 2, wherein said component (B) is an organopolysiloxane represented by the following structural formula (3):

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 $R_3^7 SiO(R_2^8 SiO)_m SiR_3^7$ 

(3)

(wherein  $R^7$  and  $R^8$  are the same or different  $C_{1\mbox{-}20}$  organic groups, at least two of which are

univalent hydrocarbon groups with epoxy groups that are free of aromatic rings, and «m» is an

integer between 0 and 1000).

18. (Previously Presented) The curable silicone composition according to Claim 2, wherein

component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) is used in

an amount of 0.01 to 100 parts by weight per 100 parts by weight of component (A).

19. (Previously Presented) The curable silicone composition according to Claim 2, wherein said

univalent hydrocarbon group with epoxy group of said component (B) is an alkyl group bonded

to a glycidoxy group or an alkyl group bonded to 3,4-epoxycyclohexyl group.

20. (Previously Presented) The curable silicone composition according to Claim 2, which is a

liquid or a paste.

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